

Before Getting Started

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Scope Probe Connections

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Scope Probe Test Points (TP) are provisioned across all inputs, outputs and VDD/VH to ground.

SCOPE PROBE CONNECTIONS

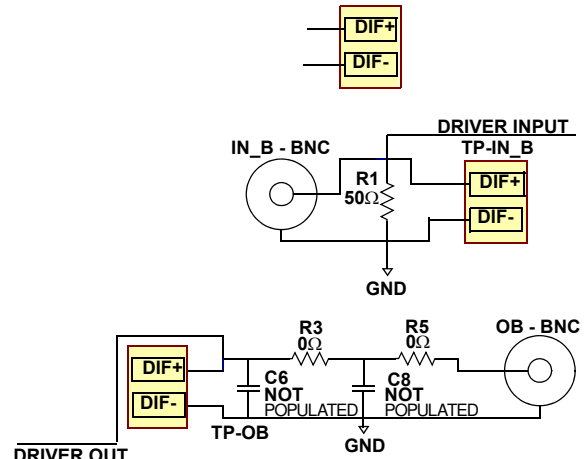


FIGURE 1. DUAL .1" SPACED PINS ARE PLACED ON THE EVALUATIONS BOARDS FOR LEADLESS ACTIVE PROBE CONNECTIONS

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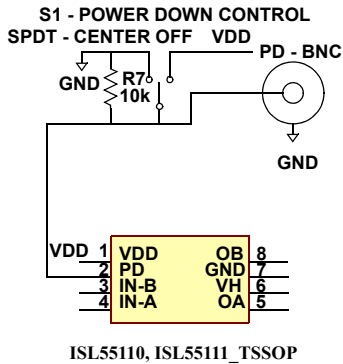


FIGURE 2. TSSOP AND QFN EVALUATION BOARDS HAVE THE SAME POWER DOWN CIRCUITRY

Finally the center off position provides a means of connecting a repetitive signal source to the PD input. This is so that the user can observe Power Down Enable/Disable timing. An important note to remember when using the PD - BNC: 1) Place the switch in Center-Off position. 2) The PD input is referenced to VDD and ground.

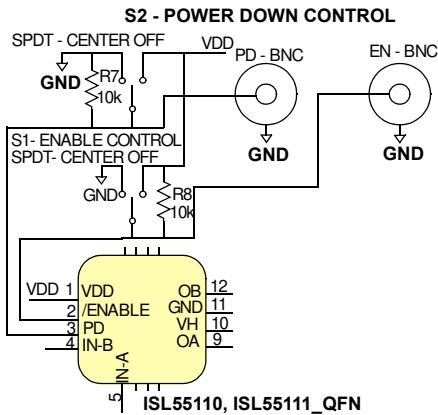


FIGURE 3. QFN PACKAGES HAVE BOTH POWER DOWN AND OUTPUT ENABLE DIGITAL INPUTS

Initial Power Up

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Schematic Information

Schematics are drawn with physical location in mind. Any changes in electrical circuitry will be updated in this document as needed.

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Driver Loads

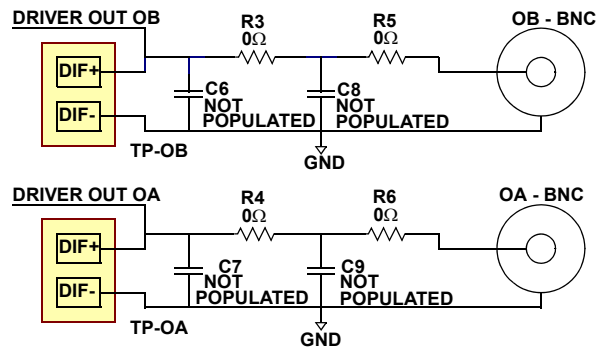


FIGURE 4. CUSTOM LOAD COMPONENTS

Component locations C6 to C7 and R3 to R6 are surface mount locations provided so the user can experiment with various load configurations.

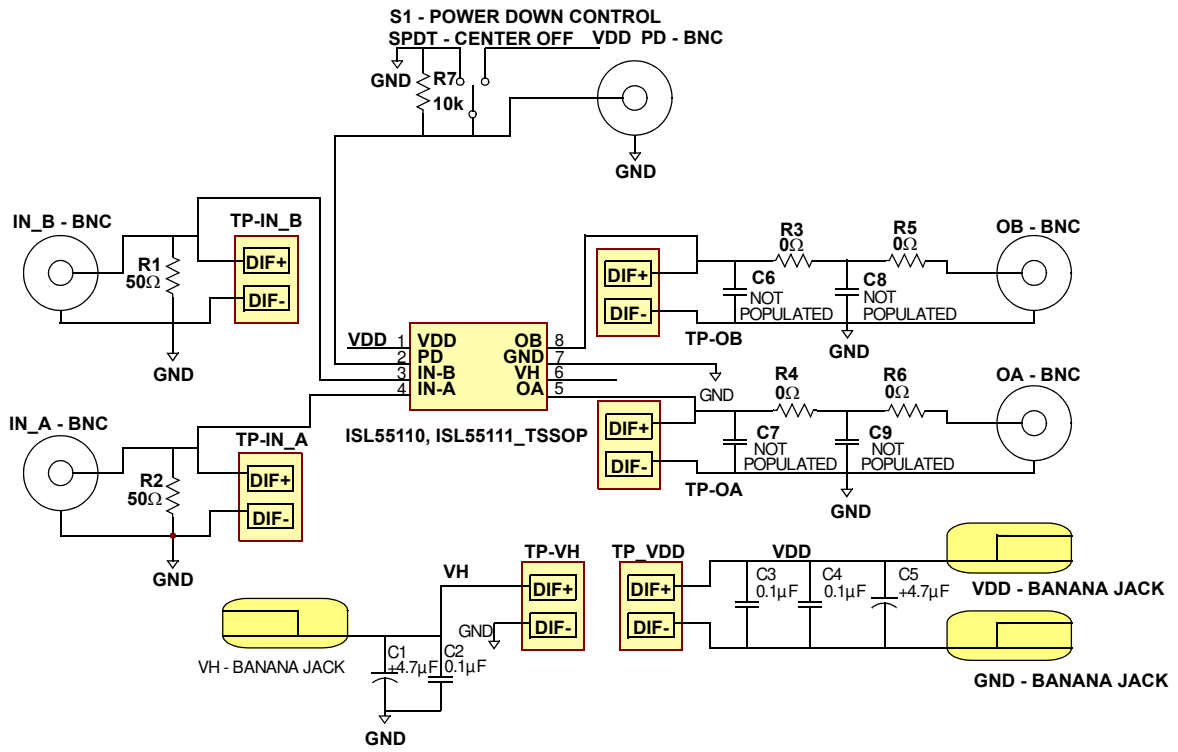


FIGURE 5. TSSOP EVALUATION BOARD SCHEMATIC

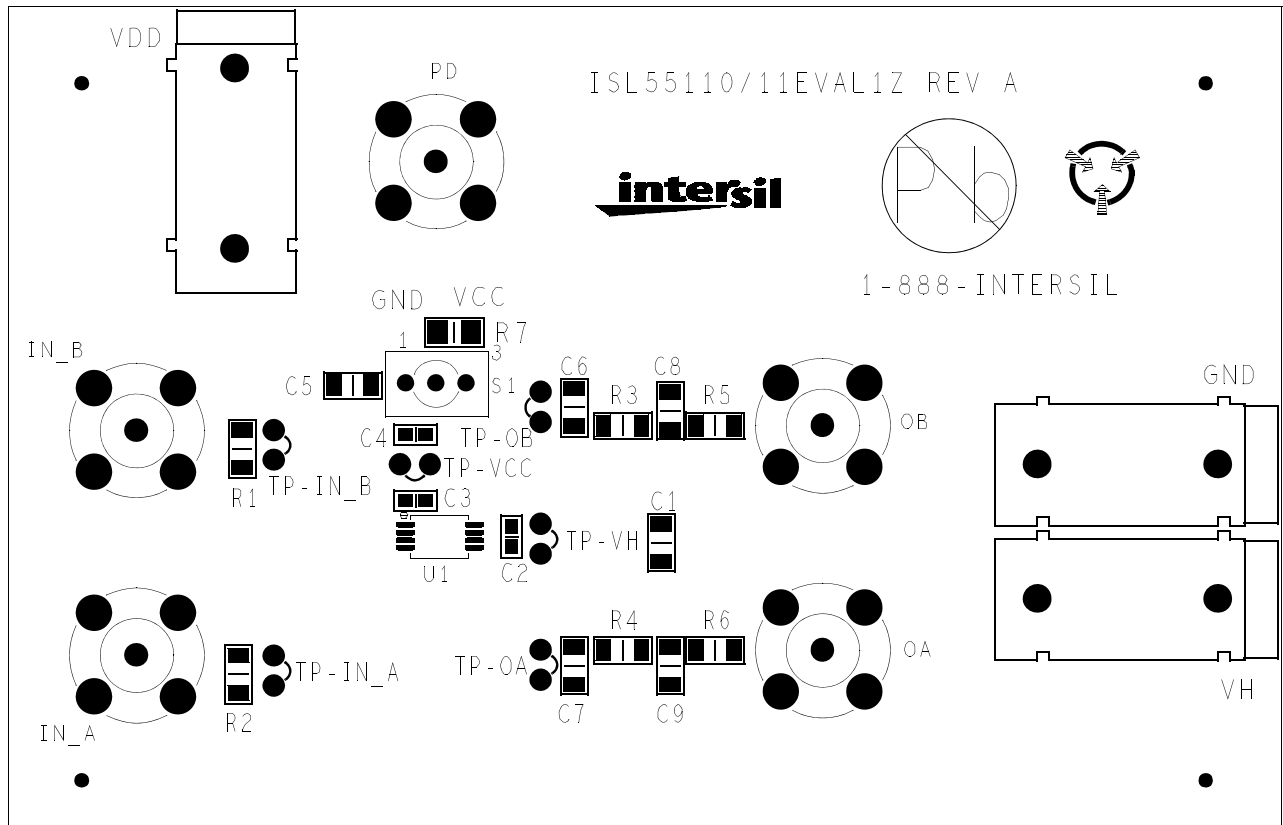


FIGURE 6. TSSOP LAYOUT

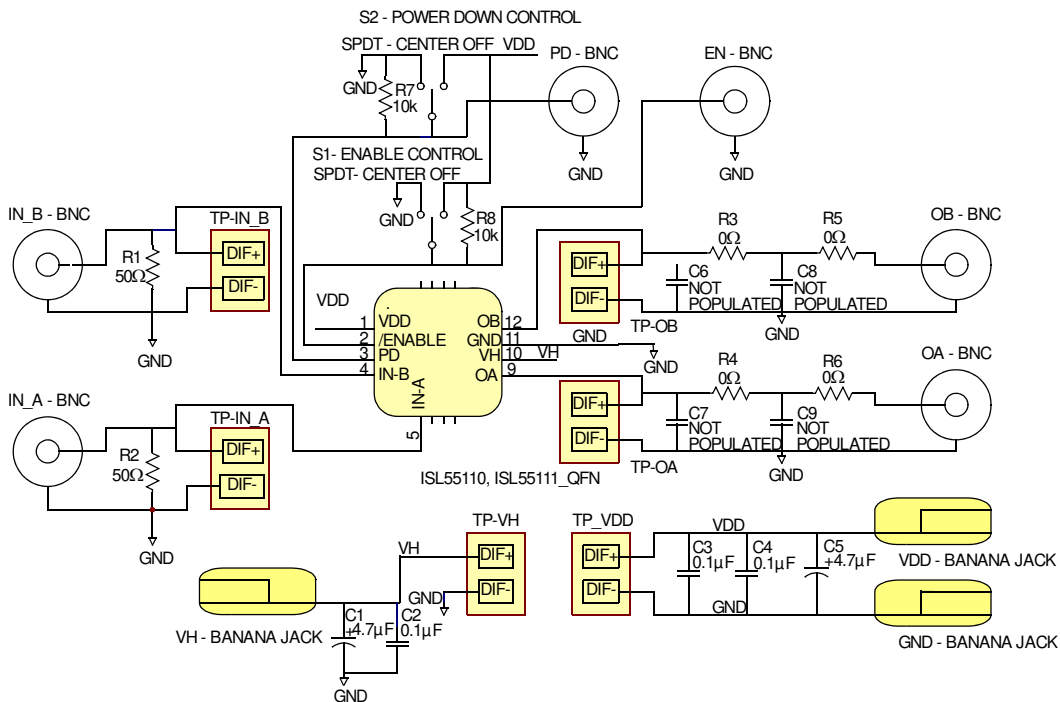


FIGURE 7. QFN EVALUATION BOARD SCHEMATIC

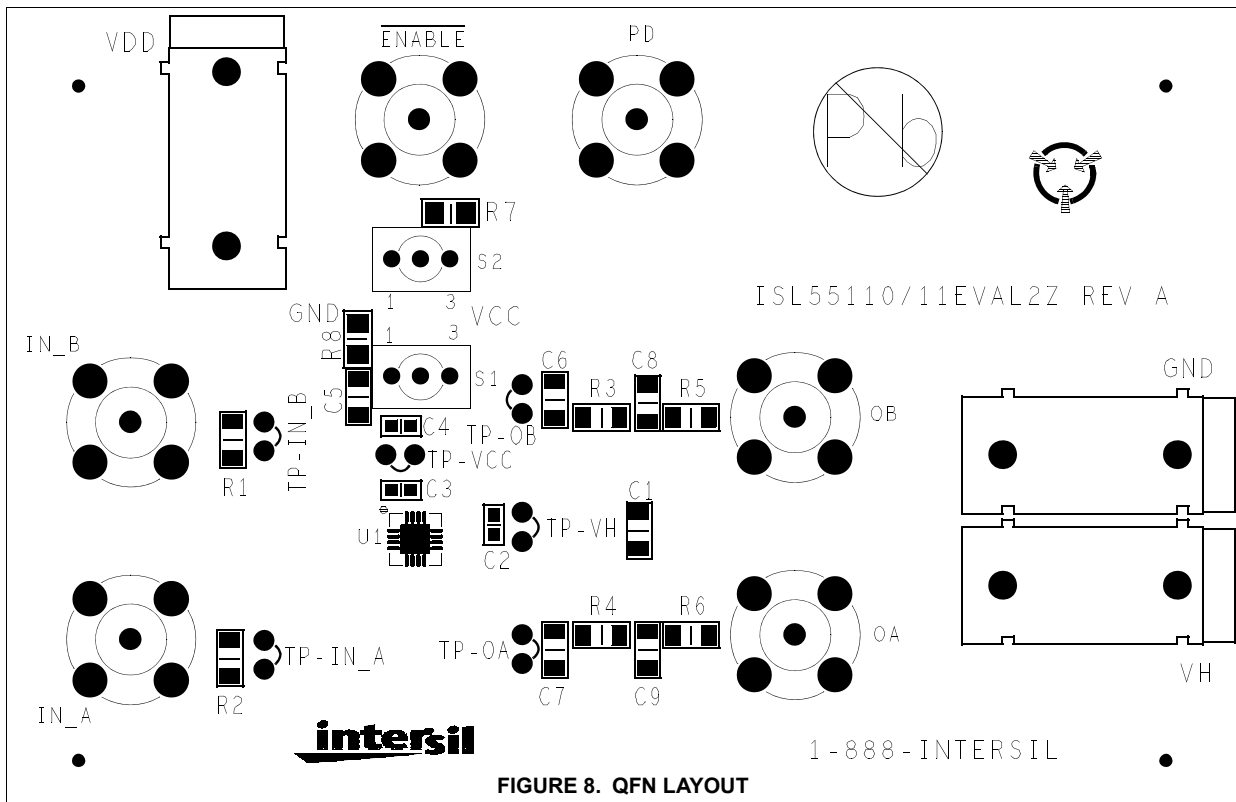


FIGURE 8. QFN LAYOUT

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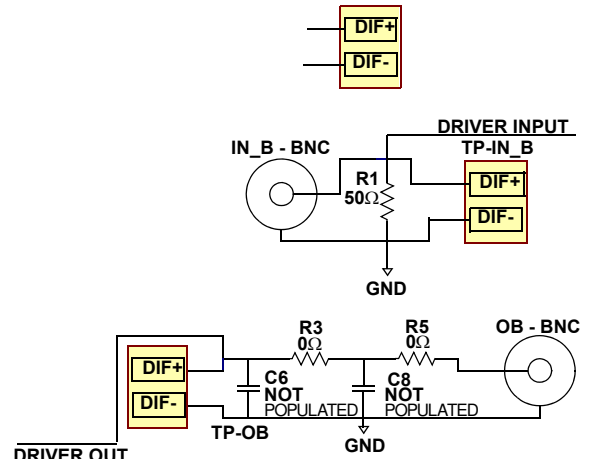


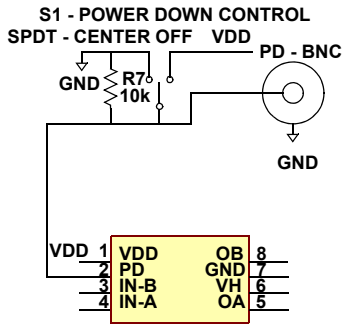
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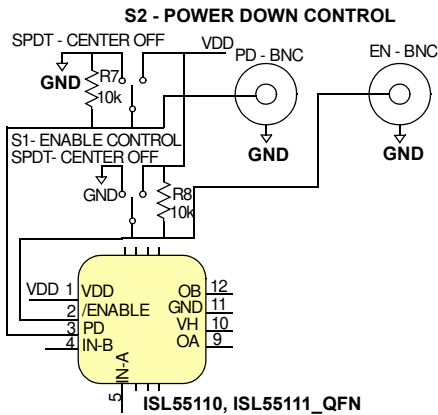
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ISL55110, ISL55111_TSSOP

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ISL55110, ISL55111_QFN

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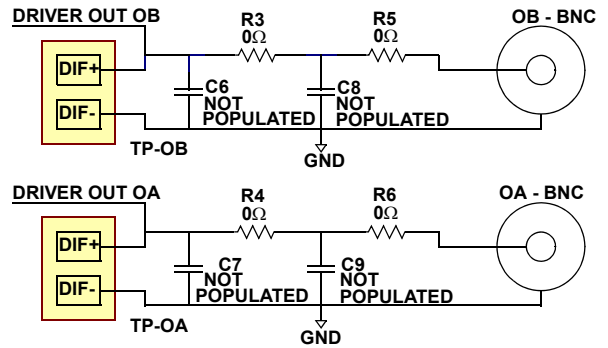


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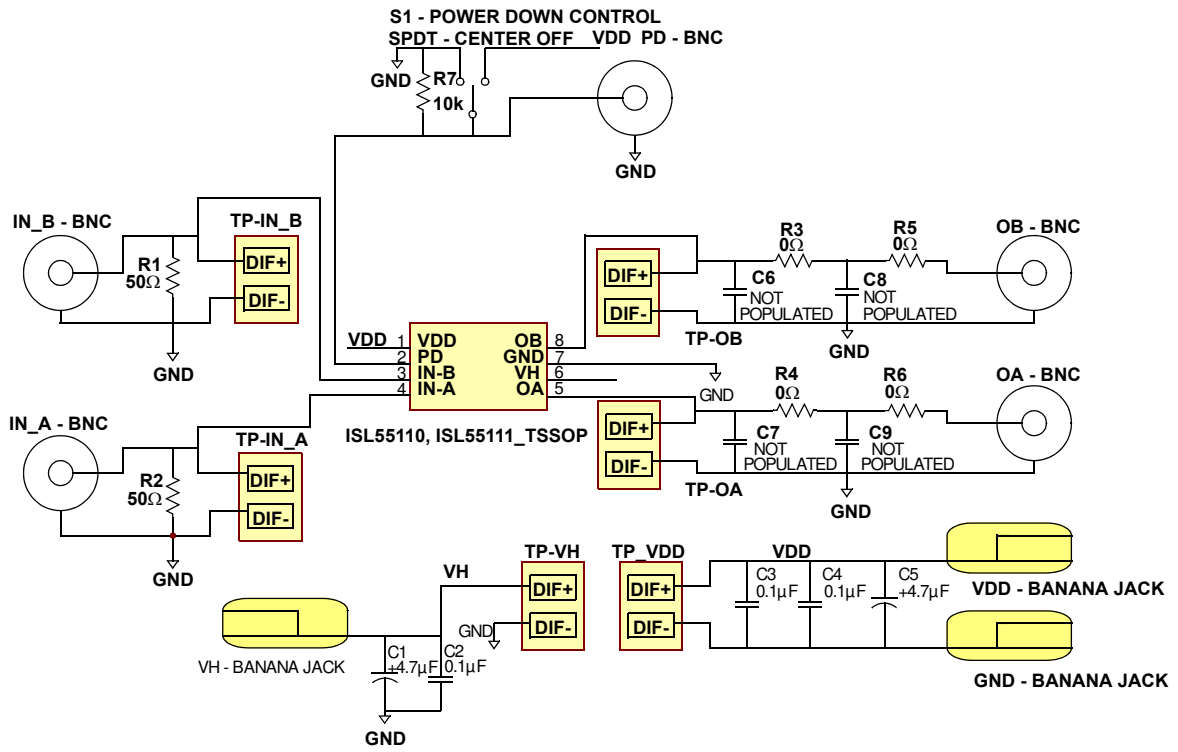


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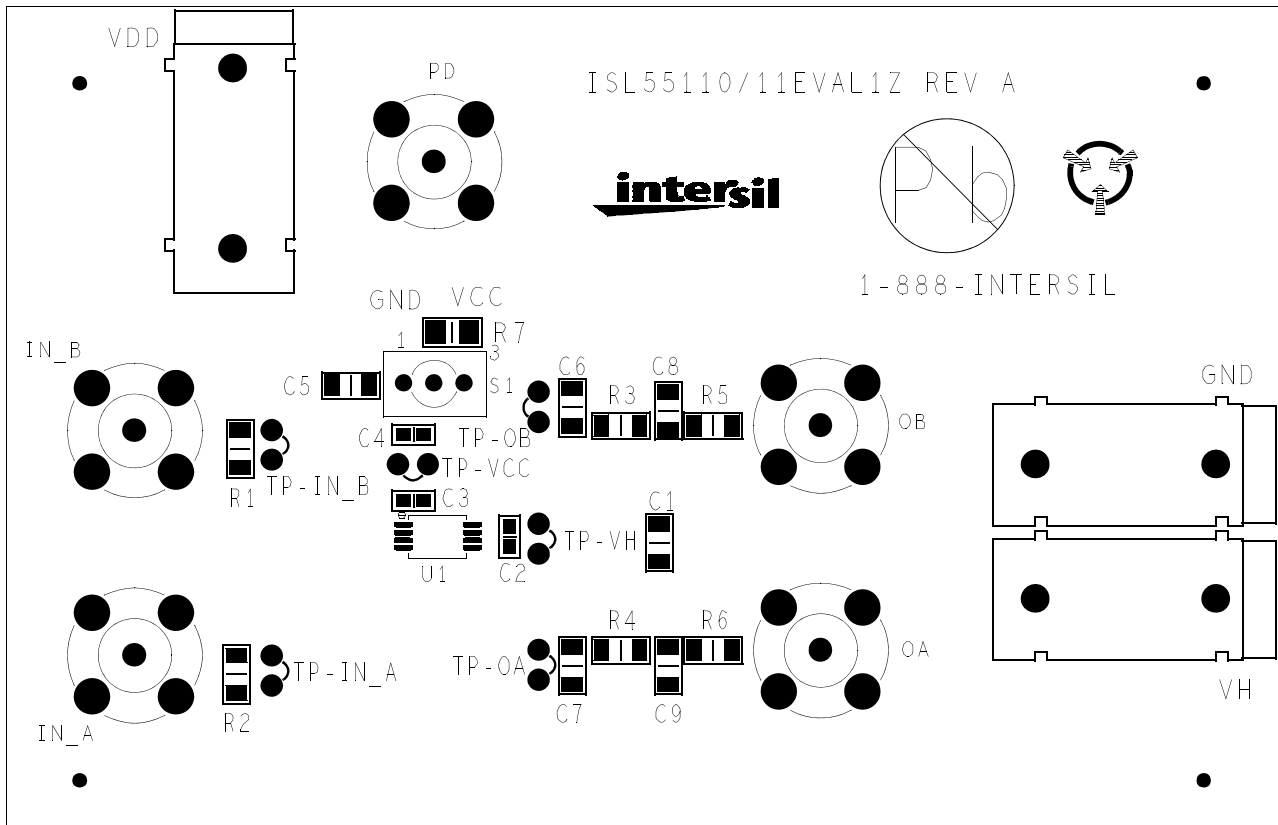


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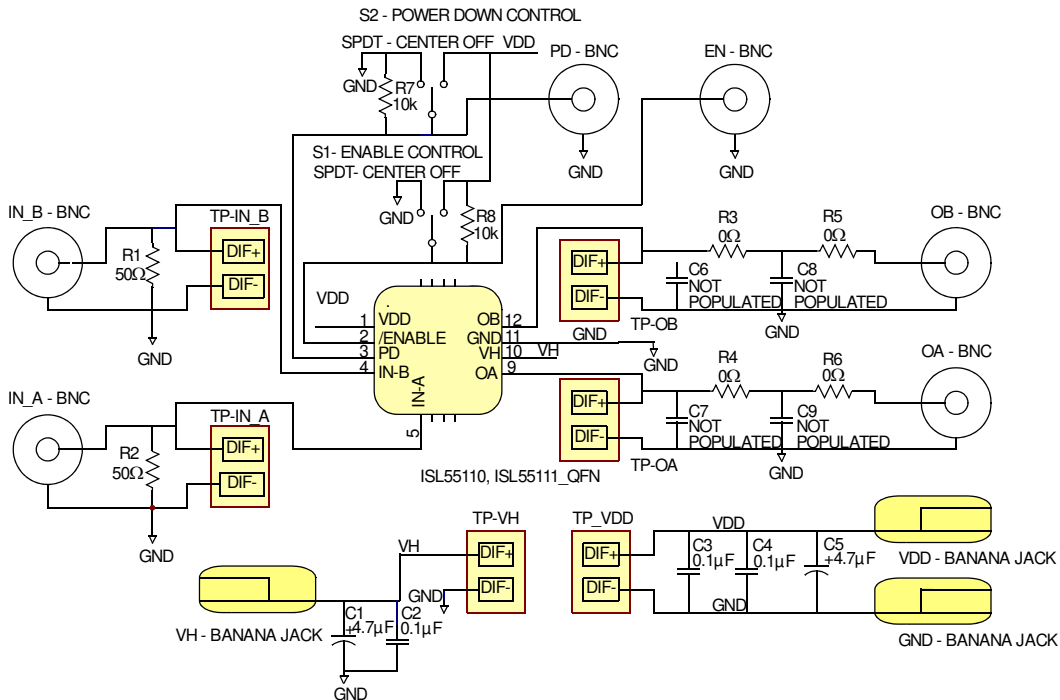


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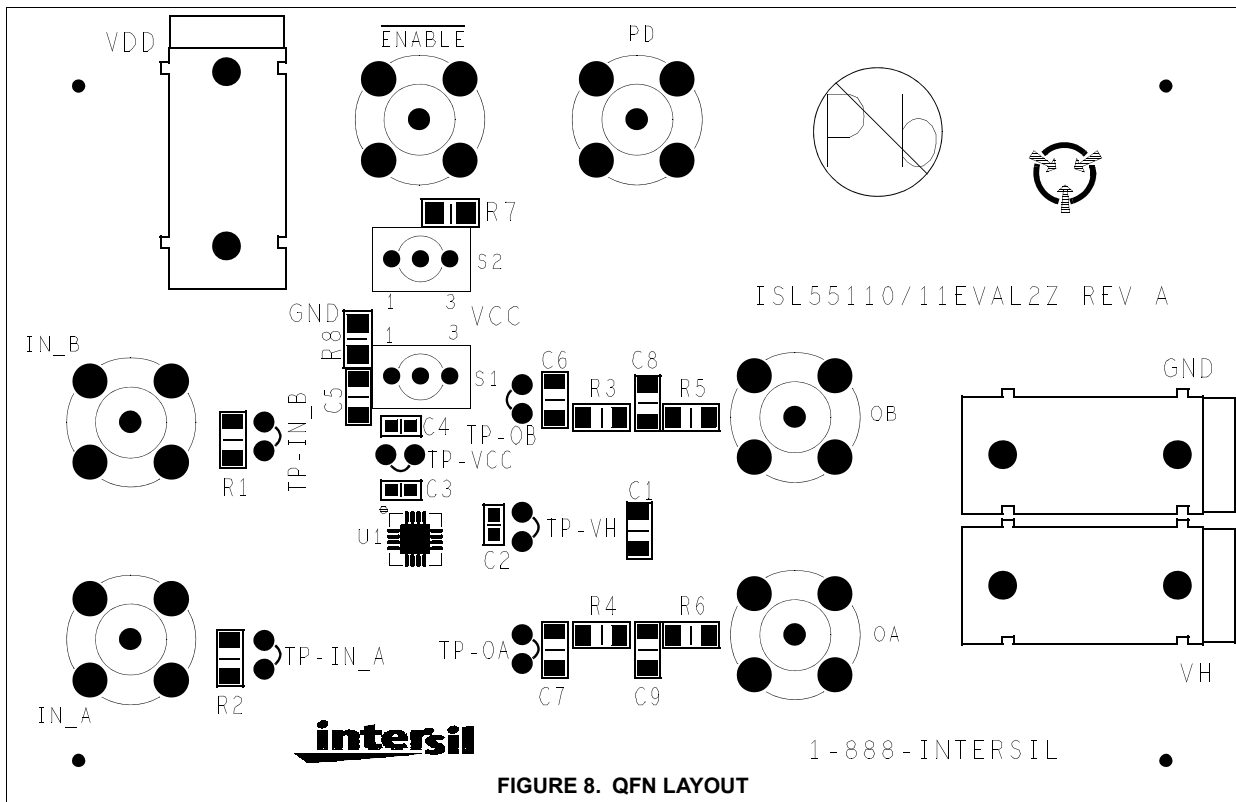


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